

VI TELEFILTER**Filter specification****TFS 211 B****1/5****Measurement condition**

Ambient temperature: 20 ... 25 °C
 Input power level: 5 ± 2 dBm
 terminating impedances
 Source: 1000 Ω || -6.8 pF
 Load: 670 Ω || -6.2 pF

Construction and pin connection

see page 2

Characteristics

Remark:

Reference level for the relative attenuation a_{rel} of the TFS 211 B is the minimum of the pass band attenuation a_{min} . The minimum of the pass band attenuation a_{min} is defined as the insertion loss a_e . The centre frequency f_C is the arithmetic mean value of the upper and lower frequencies at the 3 dB filter attenuation level relative to the insertion loss a_e . The given values for the relative attenuation a_{rel} and for the group delay ripple have to be reached at the frequencies given below also if the centre frequency f_0 is shifted due to the temperature coefficient of frequency TC_f in the operating temperature range and due to a production tolerance for the centre frequency f_0 .

D a t a		typ. value	limit
Insertion loss	$a_e = a_{min}$	6 dB dB	max. 8 dB
Center frequency	f_C	-	210,95 ... 211,05 MHz
Relative attenuation	a_{rel}		
$f_C - 100$ kHz ... $f_C + 100$ kHz		0,3...0,5 dB	max. 1 dB
$f_C - 400$ kHz ... $f_C + 400$ kHz			max. 3 dB
$f_C \pm 630$ kHz ... $f_C \pm 1,0$ MHz		-	min. 6 dB
$f_C \pm 1,0$ MHz ... $f_C \pm 2,0$ MHz		-	min. 10 dB
$f_C \pm 2,0$ MHz ... $f_C \pm 80$ MHz		-	min. 30 dB
$f_C + 80$ MHz ...	$2,0$ GHz	-	min. 40 dB
Group delay ripple GD			
$f_C - 100$ kHz ... $f_C + 100$ kHz	-	250ns	max. 350 ns
Input power level		-	max. + 10 dBm
Permissible DC voltage		-	max. 10 V
Operating temperature range			-10 °C ... + 85 °C
Storage temperature range			- 30 °C ... + 85 °C
Temperature coefficient	TC	- 0,036 ppm/K ² 1)	
Frequency inversion temperature	T_0	40 °C	-

Note 1) - Δf (Hz) = TC (ppm/K²) x (T - T₀)² x F_{T₀} (MHz)**Generated:** _____**Checked / approved:** _____

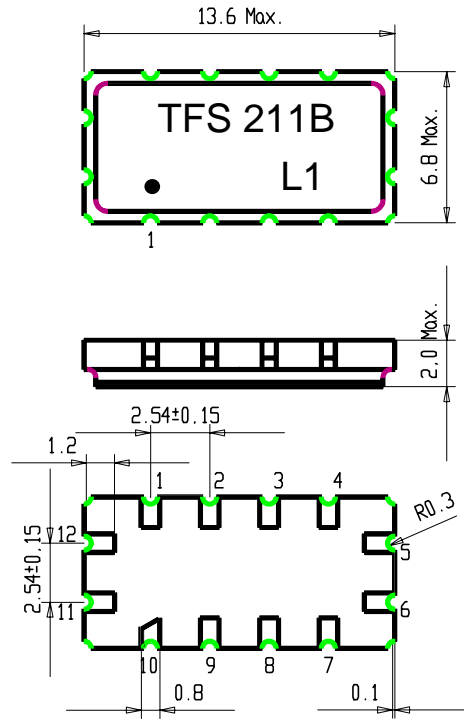
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Construction and pin connection

(All dimensions in mm)

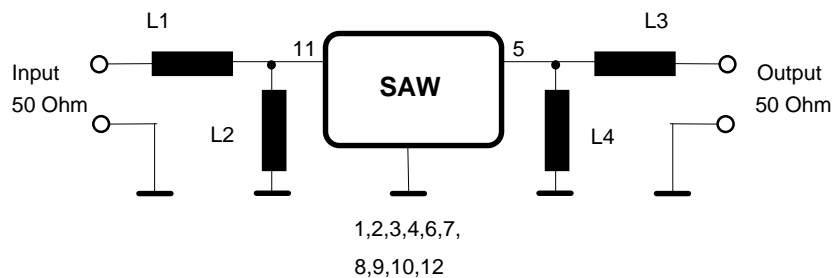


1	Ground
2	Ground
3	Ground
4	Ground
5	Output
6	Output RF Return
7	Ground
8	Ground
9	Ground
10	Ground
11	Input
12	Input RF Return

50 Ω test circuit1

The values of the matching elements which are given below are calculated from the source and load impedance. If the values of the matching elements are not equal to standard values the best standard values are given in brackets. If standard matching elements instead of the exact values are used it can not be guaranteed that the specification will be fulfilled.

Because these are theoretical values they have to be modified on PCB's corresponding to the existing parasitics.



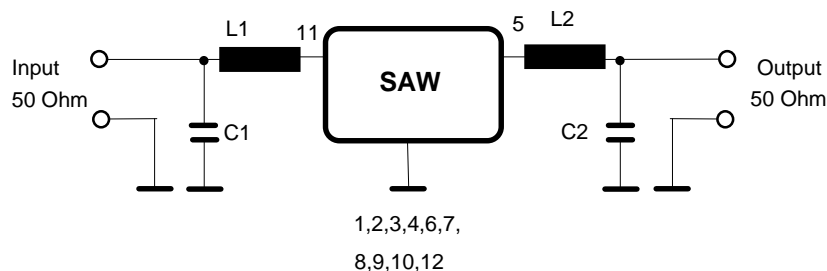
$$L1 = 150 \text{ nH}$$

$$L3 = 140 \text{ nH (150 nH)}$$

$$L2 = 220 \text{ nH}$$

$$L4 = 220 \text{ nH}$$

This circuit is used for all measurements at Telefilter.

50 Ω test circuit2

If this kind of matching circuit is used the filter will also fulfill the specification in passband. But in the stopband at $f_c + 80\text{MHz} \dots f_c + 2\text{GHz}$ the specification can't be fulfilled without using an additional lowpass. If no lowpass is used the typical attenuation in that area will be about 30 dB.

Stability Characteristics

After the following tests the filter shall meet the whole specification:

1. Shock: 30g, 18 ms, half sine wave, 3 shocks each plane;
DIN IEC 68 T2 - 27
2. Vibration: 10 Hz to 500 Hz, 0,075 mm or 1g respectively, 1 octave per min, 10 cycles per plan, 3 plans;
DIN IEC 68 T2 - 6
3. Damp heat: 90 % to 95 % rel. humidity, 40 °C, 10 days;
(steady state) DIN IEC 68 - 2 - 3
4. Resistance to solder heat (reflow): max. 2 times reflow process;
for temperature conditions refer to the attached "Air reflow temperature conditions" on sheet 4;

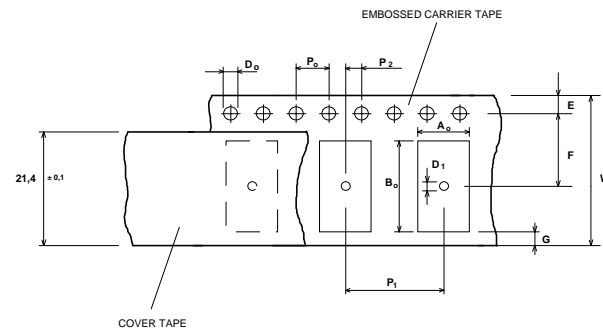
Packing

Tape & Reel: DIN IEC 286 - 3, with exception of value for N and minimum bending radius;
tape type II, embossed carrier tape with top cover tape on the upper side;

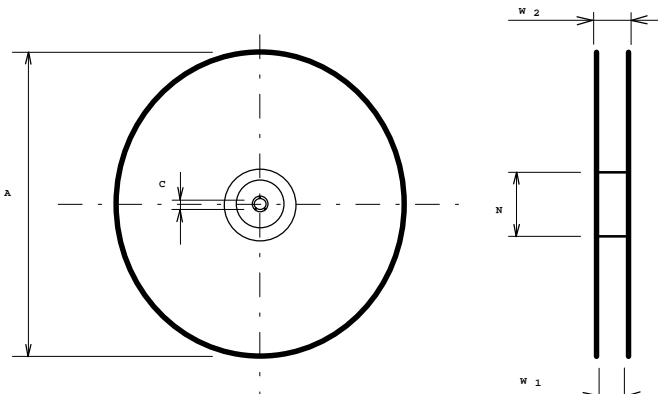
max. pieces of filters per reel: 1700

Tape (all dimensions in mm)

W	:	24	± 0,3
Po	:	4	± 0,1
Do	:	1,5	+ 0,5
D1	:	1,5	+ 0,5
E	:	1,75	± 0,1
F	:	11,5	± 0,1
G (min)	:	0,75	
P2	:	2	± 0,1
P1	:	12	± 0,1
D1(min)	:	1,5	
Ao	:	7,1	± 0,2
Bo	:	13,9	± 0,2

**Reel (all dimensions in mm):**

A	:	330
W1	:	24,4 +2
W2 (max)	:	30,4
N (min)	:	≥ 90
C	:	13 ± 0,25 ^A



The minimum bending radius is 45 mm. The mounting surface of the filters faces the bottom side of the embossed carrier tape. The marking of the filters is able to read if the view is directed on the upper side of the carrier tape with the sprocket holes on the right side of the tape.

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Air reflow temperature conditions

1st and 2nd air reflow profile

Name:	pre-heating periods	main-heating periods	peak temperature
Temperature:	150 °C - 170 °C	over 200 °C	255 °C ± 5 °C
Time:	60 sec. - 90 sec.	20 sec. - 25 sec.	

Chip-mount air reflow profile

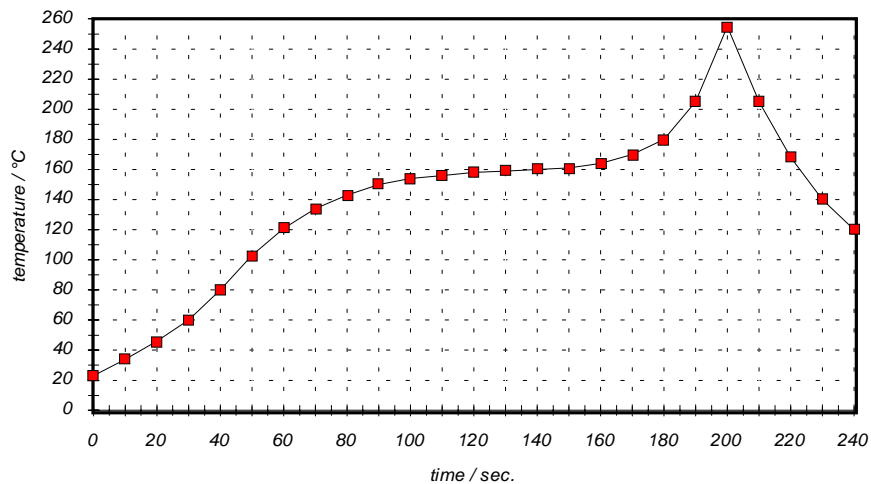


Table for temperature vs. time during the air reflow process

Tolerance of temperatures: ± 5 °C

time / sec.	temperature / °C	time / sec.	temperature / °C
0	23	140	160
10	34	150	161
20	46	160	164
30	60	170	170
40	80	180	180
50	103	190	205
60	121	195	230
70	134	200	255
80	143	205	230
90	150	210	205
100	154	215	180
110	156	220	165
120	158	230	140
130	159	240	120